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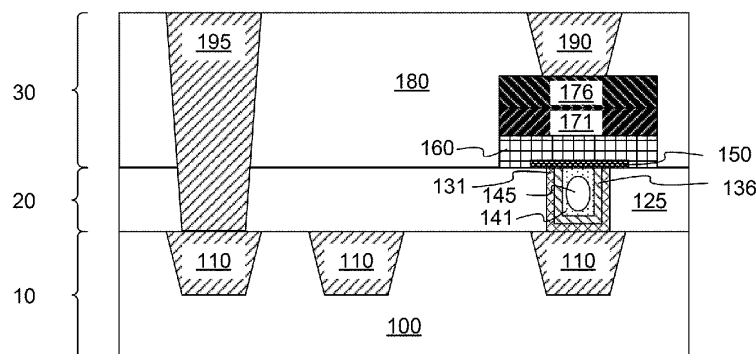


FIG. 9

(57) Abstract: An embodiment of the invention may include a semiconductor structure. The semiconductor structure may include a phase change element located above a heater. The heater may include a conductive element surrounding a dielectric element. The dielectric element may include an air gap.

WO 2022/200145 A1